

	Type	L #	Hits	Search Text	DBs
1	BRS	L1	14844	bump near8 bond\$9	US- PGPUB; USPAT; USOCR
2	BRS	L2	131	1 and sensor near8 align\$9	US- PGPUB; USPAT; USOCR
3	BRS	L3	809	chip with (align or aligned or alignment) same bump near8 (bond or bonding)	US- PGPUB; USPAT; USOCR
4	BRS	L4	490	chip with (align or aligned or alignment) with bump near8 (bond or bonding)	US- PGPUB; USPAT; USOCR
5	BRS	L5	384	chip near8 (align or aligned or alignment) with bump near8 (bond or bonding)	US- PGPUB; USPAT; USOCR
6	BRS	L6	124	chip near8 (output or contact) near8 (align or aligned or alignment) with bump near8 (bond or bonding)	US- PGPUB; USPAT; USOCR
7	BRS	L7	0	(optic or optical) with chip near8 (output or contact) near8 (align or aligned or alignment) with bump near8 (bond or bonding)	US- PGPUB; USPAT; USOCR
8	BRS	L8	0	chip near8 (output or contact) near8 (optic or optical) near8 (align or aligned or alignment) with bump near8 (bond or bonding)	US- PGPUB; USPAT; USOCR

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9	BRS	L9	0	chip near8 (output or contact) with (optic or optical) near8 (align or aligned or alignment) with bump near8 (bond or bonding)	US-PGPUB; USPAT; USOCR
10	BRS	L10	0	chip with (output or contact) with (optic or optical) near8 (align or aligned or alignment) with bump near8 (bond or bonding)	US-PGPUB; USPAT; USOCR